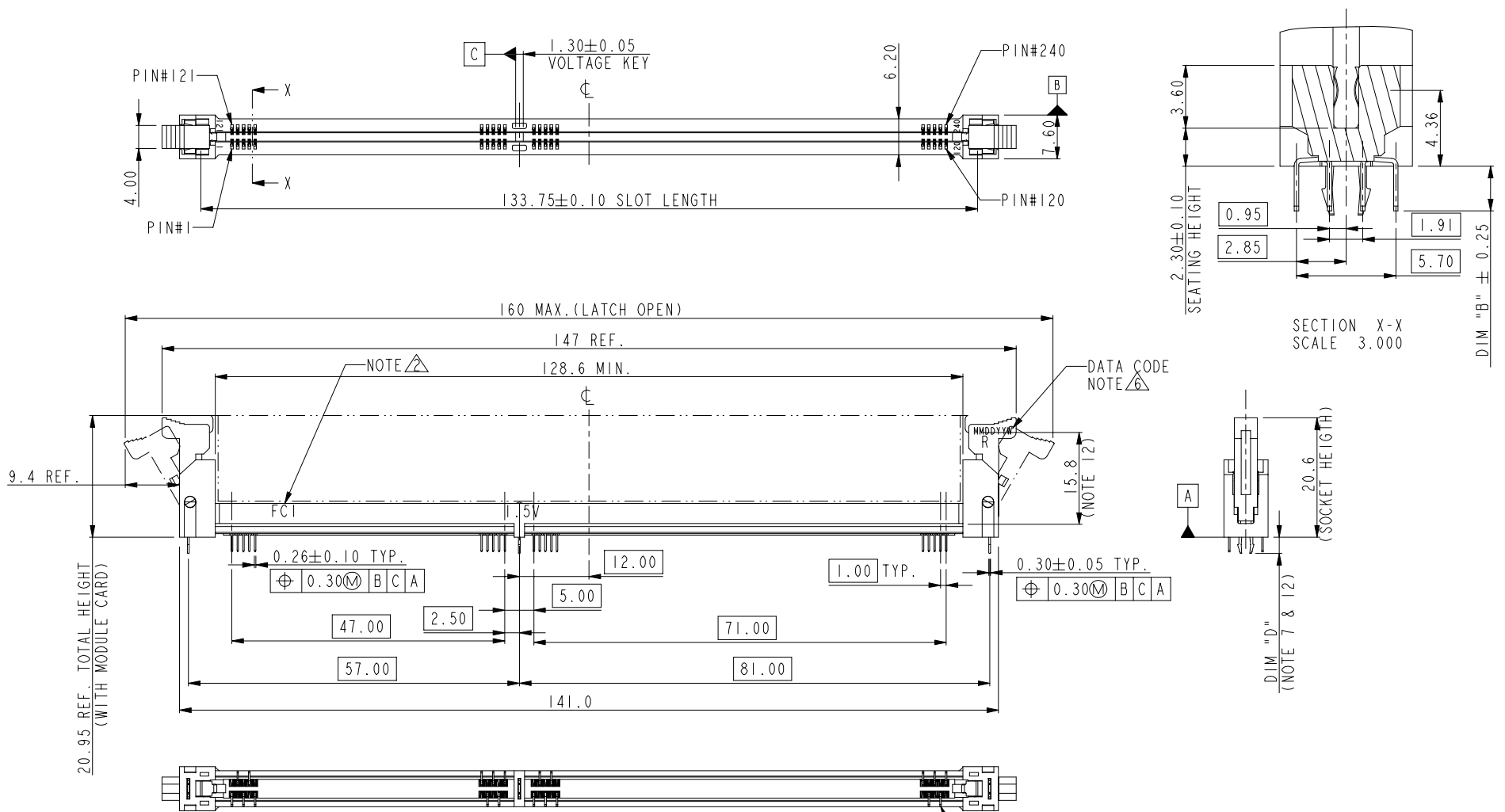




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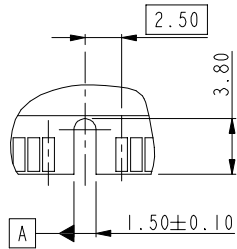
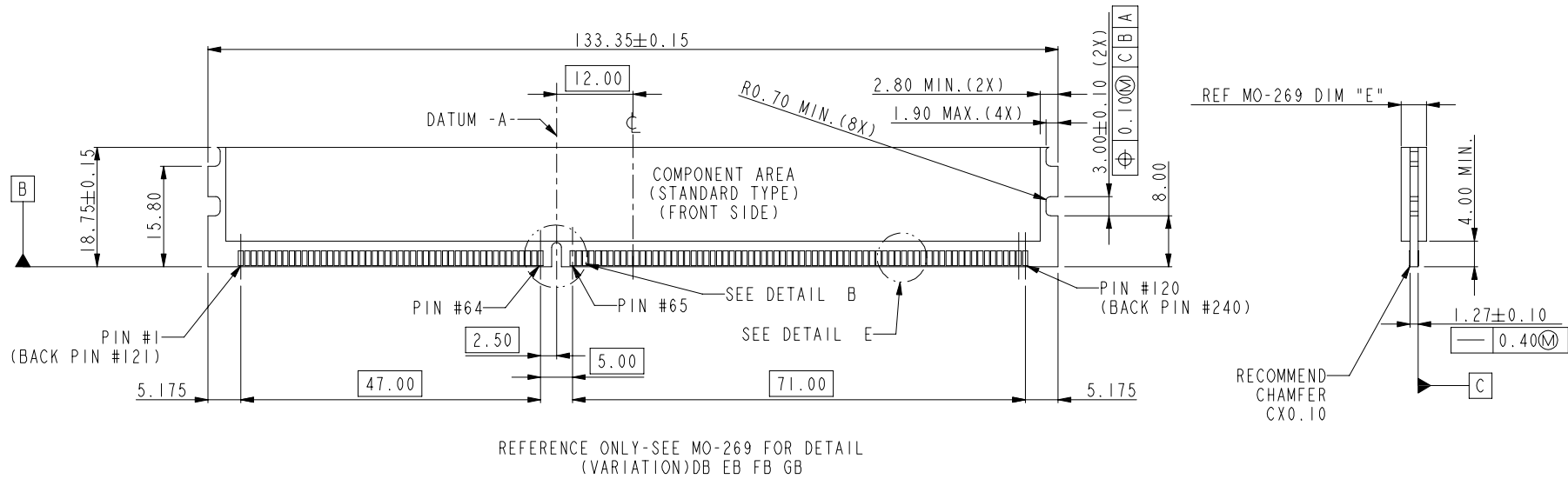


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H	T10-0047	R C	03/24/2010
J	ELX-DG-18042-1	ST	05/27/2014
K	ELX-DG-20235	ST	02/10/2015

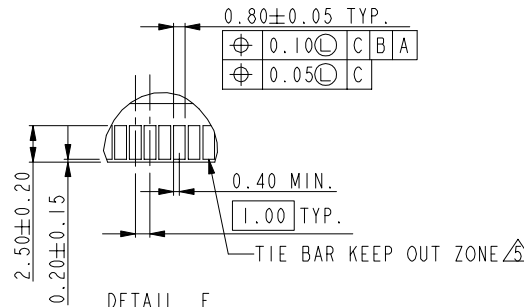
www.fciconnect.com				surface - ✓	tolerance std	projection	MM
TOLERANCES UNLESS OTHERWISE SPECIFIED				ANGULAR	0.X ±0.38	size	Scale
Dr	STONE	LI	02/10/2015	LINEAR	0.XX ±0.25	A4	0.707
Eng	STONE	LI	02/10/2015	0° ±5°	0.XXX ±0.13	ECN	/
Chr	ARAY	ZHANG	02/10/2015	Product family	-	Spec ref	*
Appr	Collins	Lu	02/10/2015	FCI title VERY LOW PROFILE (VLP) T.H DDR3, 240P SOCKET (FOR RDIMM MOUDLE) dwg no 10079192 Rev. K			
				catalog no	-	CUSTOMER	sheet 1 of 4



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DETAIL B  
SCALE 2.000



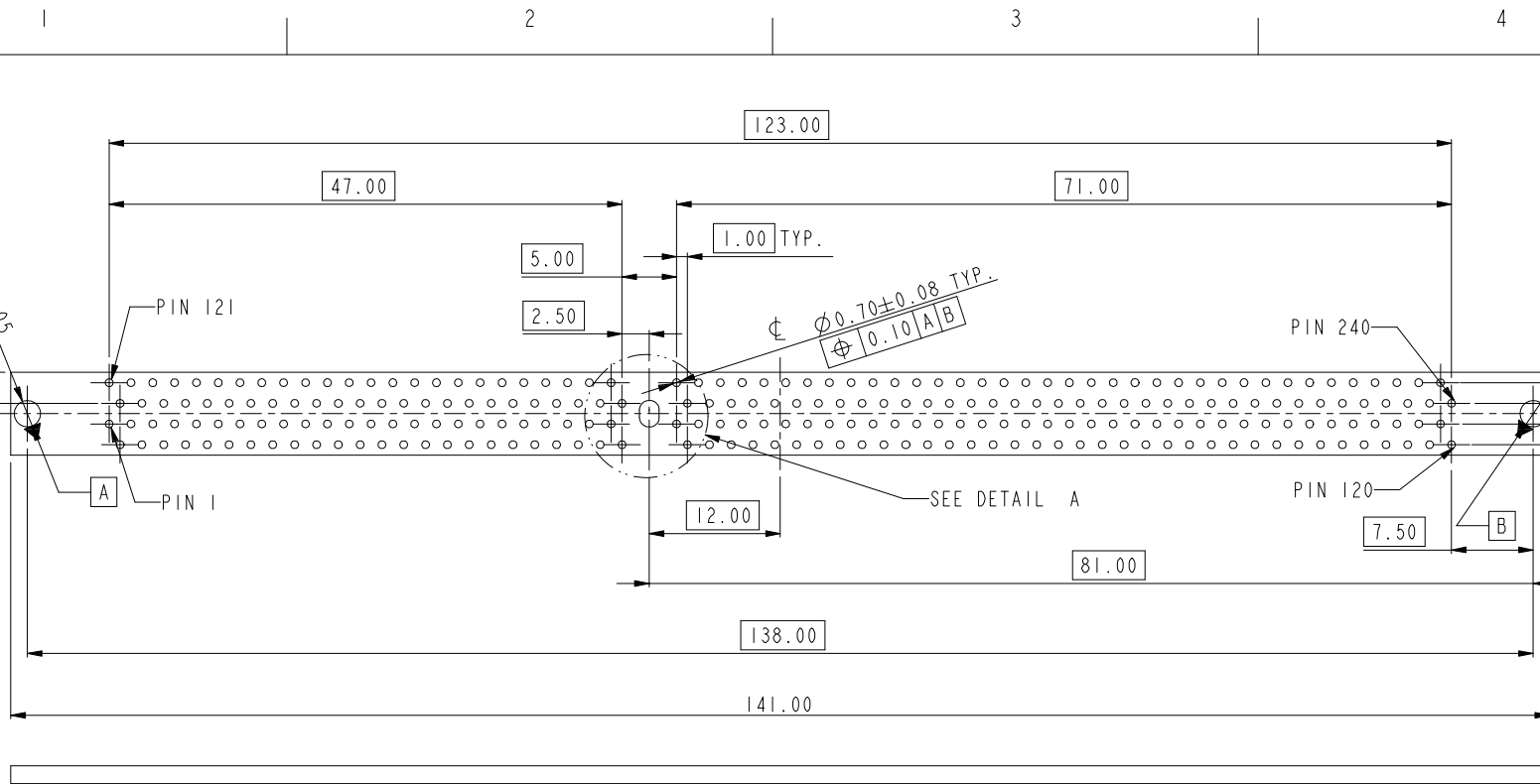
DETAIL E  
SCALE 2.000

www.fciconnect.com				surface	tolerance std	projection	MM
				✓		⊕	
				TOLERANCES UNLESS OTHERWISE SPECIFIED			
Dr	STONE	LI	02/10/2015	ANGULAR	0.X	±0.38	size
Eng	STONE	LI	02/10/2015	LINEAR	0.XX	±0.25	A4
Chr	ARAY	ZHANG	02/10/2015	0° ±5°	0.XXX	±0.13	ECN
Appr	Collins	Lu	02/10/2015	Product family		-	Spec ref
				Product family		-	Spec ref
FCI				title		10079192	
				VERY LOW PROFILE (VLP) T.H. DDR3, 240P SOCKET (FOR RDIMM MOUDLE)		Rev. K	
				catalog no		CUSTOMER	
						sheet 2 of 4	

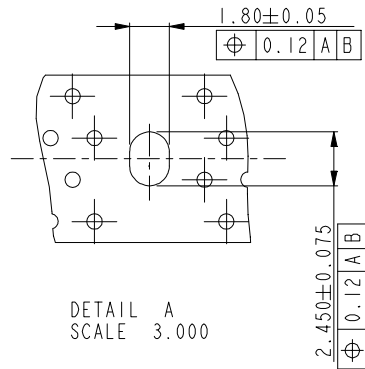


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RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



www.fciconnect.com				surface	-	tolerance std	projection	MM
				TOLERANCES UNLESS OTHERWISE SPECIFIED				Scale
Dr	STONE	LI	02/10/2015	ANGULAR	0.X	±0.38	size	A4
Eng	STONE	LI	02/10/2015	LINEAR	0.XX	±0.25	ECN	0.707
Chr	ARAY	ZHANG	02/10/2015	0° ±5°	0.XXX	±0.13	Product family	/
Appr	Collins	Lu	02/10/2015	Product family		-	Spec ref	*
				title VERY LOW PROFILE (VLP) T.H DDR3, 240P SOCKET (FOR RDIMM MOUDLE)		dwg no 10079192		Rev. K
catalog no				-		CUSTOMER		sheet 3 of 4

10079192 - □ □ □ □

STYLE : MECHANICAL KEYING

1 : 1.5 VOLT. W/ CENTER KEY

CONTACT & FORKLOCK LENGTH

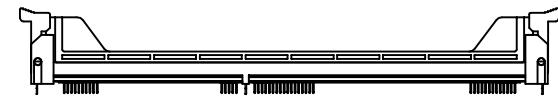
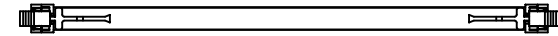
CODE	DIM "B"	DIM "D"	PCB THICKNESS
00	2.67 mm	3.50 mm	1.60 mm (0.063")
11	3.18 mm	4.00 mm	2.36 mm (0.093")

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
2LF	15u" (0.38um) MIN. GOLD	100u" (2.54um) MIN. 100% MATTE TIN	50u" (1.27um) MIN. NICKEL OVERALL
3LF	30u" (0.76um) MIN. GOLD		
4LF	3u" (0.076um) MIN. GOLD		

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
- 1 : BLACK HOUSING + AMBER EJECTOR (NOTE. 11)
- 2 : BLACK HOUSING + BLACK EJECTOR
- 8 : IVORY HOUSING + IVORY EJECTOR
- 9 : IVORY HOUSING + BLACK EJECTOR
- 3 : BLUE HOUSING + IVORY EJECTOR
- △4 : BLACK HOUSING + IVORY EJECTOR + CAP



PRODUCT WITH CAP ILLUSTRATION

NOTES:

1. MATERIAL:  
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.  
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.  
TERMINAL: HIGH PERFORMANCE COPPER ALLOY  
METAL CLIP: COPPER ALLOY.
- △2 FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.
3. PRODUCT SPECIFICATION: GS-12-486.
4. PACKAGING SPECIFICATION: GS-14-899.
- △5 FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.
- △6 THE DATE CODE IS SHOWN "MM-DD-YY-W". "W" MEANS PRODUCTION LINE. "R" MEANS FOR 'RDIMM' SOCKET.
7. THE REQUIRED PCB THICKNESS IS 1.60MM MINIMUM FOR BOARD LOCK RETENTION.
8. THIS SOCKET MEETS APPLICABLE JEDEC STD.; SOCKET OUTLINE SO-XXX, GAUGE GS-00X AND GS-00X. (SUSPENDED BY JEDEC)
9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
10. THE HOUSING WILL WITH STAND EXPOSURE TO 260 ± 5°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDERING APPLICATION.
11. AMBER EJECTOR OPTION IS ONLY FOR SOLDERING ENVIRONMENT TEMP. UNDER 170°C.
12. FROM SEATING PLANE TO TOP MODULE CARD ENGAGEMENT.
13. THIS SOCKET CONTACT EOL RESISTANCE IS DESIGNED TO BE 20 mohm MAX.



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www.fciconnect.com				surface <input checked="" type="checkbox"/>	tolerance std	projection	MM
				TOLERANCES UNLESS OTHERWISE SPECIFIED			
Dr	STONE	LI	02/10/2015	ANGULAR	0.X	±0.38	size A4
Eng	STONE	LI	02/10/2015	LINEAR	0.XX	±0.25	Scale 1.000
Chr	ARAY	ZHANG	02/10/2015	0° ±5°	0.XXX	±0.13	ECN /
Appr	Collins	Lu	02/10/2015	Product family	-	Spec ref	*
FCI		title VERY LOW PROFILE (VLP) T.H DDR3, 240P SOCKET (FOR RDIMM MOUDLE)			dwg no 10079192		Rev. K
catalog no -				CUSTOMER		sheet 4 of 4	